CLAIMS

[Claim 1] A multi-wire wiring board insulated coated wire comprising:

a wire;

a wire coating layer disposed around the wire; and

a wire adhesive layer disposed around the wire coating layer,

wherein the wire coating layer includes a fluorine resin and the wire adhesive layer includes at least one of a fluorine resin or a polyamide-imide resin.

[Claim 2] The multi-wire wiring board insulated coated wire according to claim 1,

wherein the wire adhesive layer includes a fluorine resin.

[Claim 3] The multi-wire wiring board insulated coated wire according to claim 1 or 2,

wherein relative permittivity of the wire coating layer at 10 GHz is from 2.1 to 3.2 or relative permittivity of the wire adhesive layer at 10 GHz is from 2.6 to 3.2.

[Claim 4] A multi-wire wiring board having a microstrip structure or a strip structure, comprising:

the insulated coated wire according to any one of claims 1 to 3;

an insulation layer disposed around the insulated coated wire; and

a conductor pattern disposed on the insulation layer.

[Claim 5] A multi-wire wiring board having a strip structure, comprising:

the insulated coated wire according to any one of claims 1 to 3;

an insulation layer disposed around the insulated coated wire; and

conductor patterns disposed so as to face each other across the insulated coated wire with the insulation layer interposed therebetween.